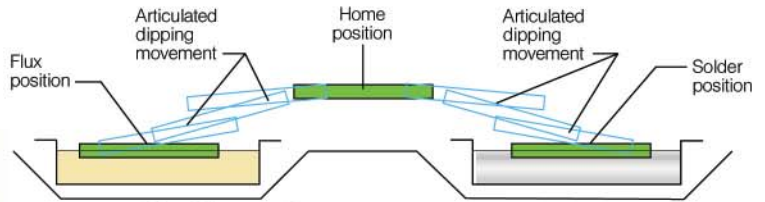




**LEAD FREE**



Using the Big Dipper membrane keypad, the operator can control solder temperature, preheat time, solder dip time and the program storage number.



Big Dipper Process

## **Big Dipper™**

Semi-automatic Model GW-BD  
Lead Free Model: GW-BD-HT

### **Features**

The Big Dipper semi-automatic soldering system completely solders entire PC boards. The microprocessor controller makes consistent and high quality soldering easy by prompting the operator throughout the entire process.

- Articulated dipping movement (see process diagram above)
- 3 stage timed process includes: flux cycle, preheat cycle, and solder cycle
- Microprocessor control with LCD display
- 12 menu storage
- Flux station with flux drain
- Stainless steel solder pot
- Pallet with adjustable titanium fingers hold PCBs

### **Big Dipper Specifications**

Power	120 VAC, 60 Hz, 10 A optional 220 VAC, 50/60 Hz, 5 A
Max solder temp	275°C (527°F)
Max solder temp lead free Model HT	350°C (662°F)
Solder capacity	approx. 50 lbs (23Kg)
Max board size	8" x 11.375" (203 x 290 mm)
Dimensions	31" x 25.25" x 24.5" (787 x 641 x 622 mm)
Warm-up time	approx. 50 min
Weight	62 lbs empty (28Kg), 112 lbs (50 Kg) with solder



## **Little Dipper™**

Model GW-LD; Lead Free Model: GW-LD-HT

### **Features**

The APS Little Dipper solder pot can be used for a variety of solder dipping applications.

- Digital closed loop temperature control
- Stainless steel solder pot
- Solder surface area: 9.375" x 13"

### **Little Dipper Specifications**

Power	120 VAC, 60 Hz, 10 A optional 220 VAC, 50/60 Hz, 5 A
Max solder temperature	275°C (527°F)
Max solder temperature lead free Model HT	350°C (662°F)
Solder capacity	approx. 50 lbs (23Kg)
Solder pot size	9.375" x 13.0" x 1.75" (238 x 330 x 44 mm)
Dimensions	16.25" x 17.5" x 9" (413 x 445 x 230 mm)
Warm-up time	Approx. 50 min
Weight	28 lbs empty (13Kg), 78 lbs (35 Kg) with solder